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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	24 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c55-xt-sp

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2.0 PIC16C5X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC16C5X Product Identification System at the back of this data sheet to specify the correct part number.

For the PIC16C5X family of devices, there are four device types, as indicated in the device number:

- 1. **C**, as in PIC16**C**54C. These devices have EPROM program memory and operate over the standard voltage range.
- LC, as in PIC16LC54A. These devices have EPROM program memory and operate over an extended voltage range.
- 3. **CR**, as in PIC16**CR**54A. These devices have ROM program memory and operate over the standard voltage range.
- 4. LCR, as in PIC16LCR54A. These devices have ROM program memory and operate over an extended voltage range.

2.1 UV Erasable Devices (EPROM)

The UV erasable versions offered in CERDIP packages, are optimal for prototype development and pilot programs.

UV erasable devices can be programmed for any of the four oscillator configurations. Microchip's

PICSTART[®] Plus⁽¹⁾ and PRO MATE[®] programmers both support programming of the PIC16C5X. Third party programmers also are available. Refer to the Third Party Guide (DS00104) for a list of sources.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers expecting frequent code changes and updates, or small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must be programmed.

Note 1: PIC16LC54C and PIC16C54A devices require OSC2 not to be connected while programming with PICSTART[®] Plus programmer.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production (SQTPSM) Devices

Microchip offers the unique programming service where a few user defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential. The devices are identical to the OTP devices but with all EPROM locations and configuration bit options already programmed by the factory.

Serial programming allows each device to have a unique number which can serve as an entry code, password or ID number.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, giving the customer a low cost option for high volume, mature products. NOTES:

6.5 Program Counter

As a program instruction is executed, the Program Counter (PC) will contain the address of the next program instruction to be executed. The PC value is increased by one, every instruction cycle, unless an instruction changes the PC.

For a GOTO instruction, bits 8:0 of the PC are provided by the GOTO instruction word. The PC Latch (PCL) is mapped to PC<7:0> (Figure 6-7, Figure 6-8 and Figure 6-9).

For the PIC16C56, PIC16CR56, PIC16C57, PIC16CR57, PIC16C757, PIC16C58 and PIC16CR58, a page number must be supplied as well. Bit5 and bit6 of the STA-TUS Register provide page information to bit9 and bit10 of the PC (Figure 6-8 and Figure 6-9).

For a CALL instruction, or any instruction where the PCL is the destination, bits 7:0 of the PC again are provided by the instruction word. However, PC<8> does not come from the instruction word, but is always cleared (Figure 6-7 and Figure 6-8).

Instructions where the PCL is the destination, or modify PCL instructions, include MOVWF PCL, ADDWF PCL, and BSF PCL, 5.

For the PIC16C56, PIC16CR56, PIC16C57, PIC16CR57, PIC16C58 and PIC16CR58, a page number again must be supplied. Bit5 and bit6 of the STA-TUS Register provide page information to bit9 and bit10 of the PC (Figure 6-8 and Figure 6-9).

Note:	Because PC<8> is cleared in the CALL
	instruction, or any modify PCL instruction,
	all subroutine calls or computed jumps are
	limited to the first 256 locations of any pro-
	gram memory page (512 words long).

FIGURE 6-7: LOADING OF PC BRANCH INSTRUCTIONS - PIC16C54, PIC16CR54, PIC16C55

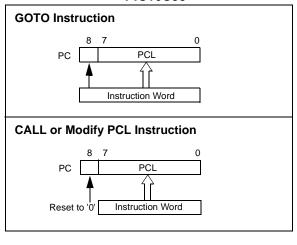


FIGURE 6-8:

LOADING OF PC BRANCH INSTRUCTIONS - PIC16C56/PIC16CR56

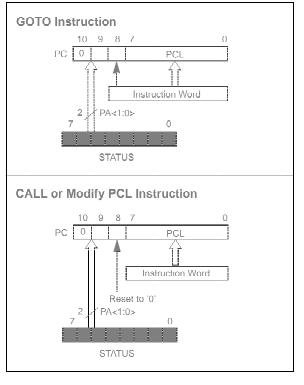
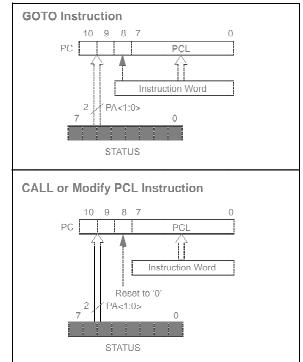


FIGURE 6-9:

LOADING OF PC BRANCH INSTRUCTIONS - PIC16C57/PIC16CR57, AND PIC16C58/ PIC16CR58



NOTES:

PIC16C5X

XORLW	e OR lite	eral with	w						
Syntax:	[<i>label</i>]	XORLW	k						
Operands:	nds: $0 \le k \le 255$								
Operation:	(W) .XOR. $k \rightarrow (W)$								
Status Affected: Z									
Encoding:	1111	kkkk	kkkk						
Description: The contents of the W register ar XOR'ed with the eight bit literal 'k The result is placed in the W regi ter.									
Words:	1								
Cycles:	1								
Example: XORLW 0xAF									
Before Instruction W = 0xB5 After Instruction W = 0x1A									

Exclusive OR W with f							
[label] XORWF f,d							
$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$							
(W) .XOR. (f) \rightarrow (dest)							
Z							
0001 10df ffff							
W register with register 'f'. If 'd' is 0 the result is stored in the W regis- ter. If 'd' is 1 the result is stored							
1							
1							
XORWF REG,1							
= 0xAF = 0xB5 on = 0x1A							
	[<i>label</i>] XORWF f,d $0 \le f \le 31$ $d \in [0,1]$ (W) .XOR. (f) → (dest) Z 0001 10df ffff Exclusive OR the contents W register with register 'f'. I the result is stored in the W ter. If 'd' is 1 the result is stored back in register 'f'. 1 1 XORWF REG, 1 interion = 0xAF = 0xB5 ion						

12.2 DC Characteristics: PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)		Standard Operating Conditions (unless otherwise specified Operating Temperature -40 °C \leq TA \leq +85°C for industrial					
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
D001	Vdd	Supply Voltage PIC16C5X-RCI PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-LPI	3.0 3.0 4.5 4.5 2.5		6.25 6.25 5.5 5.5 6.25	V V V V	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾		1.5*		V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*		—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RCI ⁽³⁾ PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI PIC16C5X-LPI		1.8 1.8 4.8 4.8 9.0 15	3.3 3.3 10 10 20 40	mA mA mA mA μA	Fosc = 4 MHz, VDD = $5.5V$ Fosc = 4 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 20 MHz, VDD = $5.5V$ Fosc = 32 kHz, VDD = $3.0V$, WDT disabled
D020	Ipd	Power-down Current ⁽²⁾	_	4.0 0.6	14 12	μΑ μΑ	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled

* These parameters are characterized but not tested.

- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

13.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS

2. Tp	ρS	
Т		
F	Frequency	T Time
Lowe	ercase letters (pp) and their meanings:	
рр		
2	to	mc MCLR
ck	CLKOUT	osc oscillator
су	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer
Uppe	ercase letters and their meanings:	
S		
F	Fall	P Period
н	High	R Rise
T	Invalid (Hi-impedance)	V Valid
L	Low	Z Hi-impedance

FIGURE 13-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16CR54A

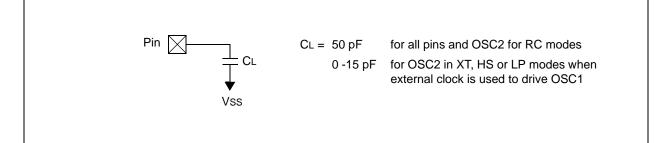


FIGURE 14-6: MAXIMUM IPD vs. VDD, WATCHDOG DISABLED

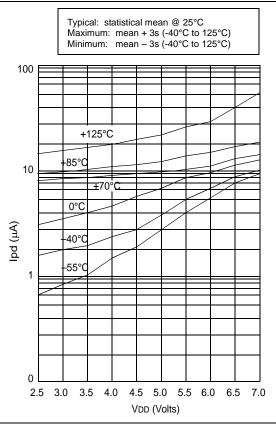


FIGURE 14-7: T

TYPICAL IPD vs. VDD, WATCHDOG ENABLED

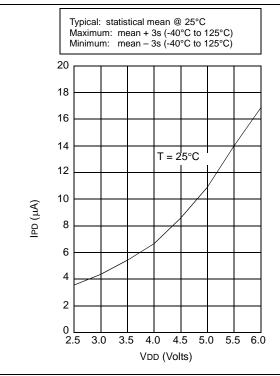
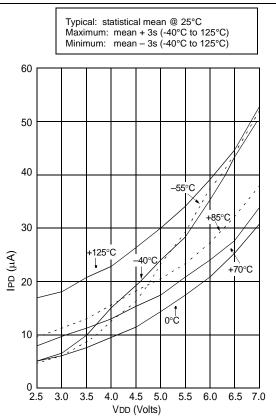


FIGURE 14-8: MAXIMUM IPD vs. VDD, WATCHDOG ENABLED



IPD, with WDT enabled, has two components: The leakage current, which increases with higher temperature, and the operating current of the WDT logic, which increases with lower temperature. At -40° C, the latter dominates explaining the apparently anomalous behavior.



FIGURE 16-17: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD

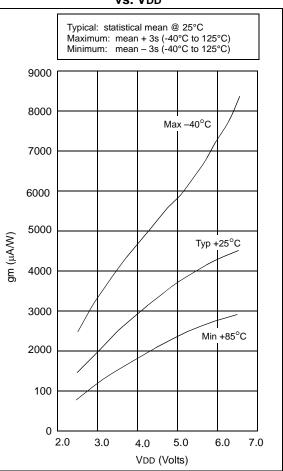


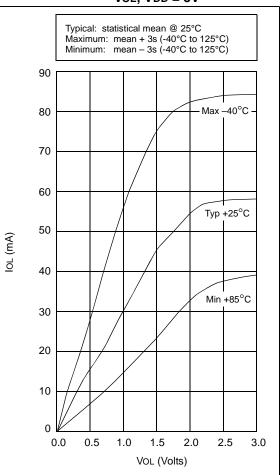


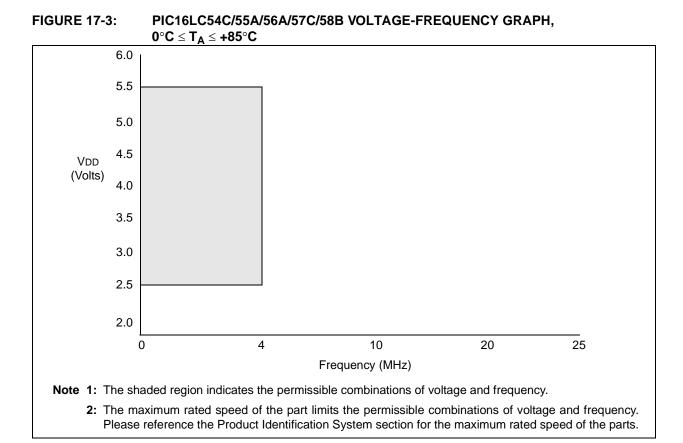
TABLE 16-2:INPUT CAPACITANCE FOR
PIC16C54A/C58A

Pin	Typical Capacitance (pF)				
FIII	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
TOCKI	3.2	2.8			

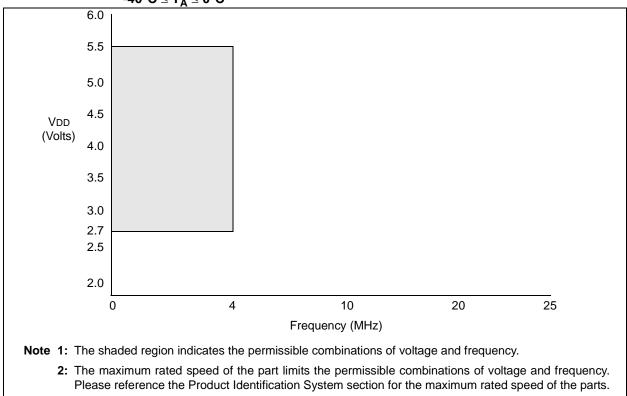
All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

FIGURE 16-23: PORTA, B AND C IOL vs. VoL, VDD = 5V









17.5 Timing Diagrams and Specifications

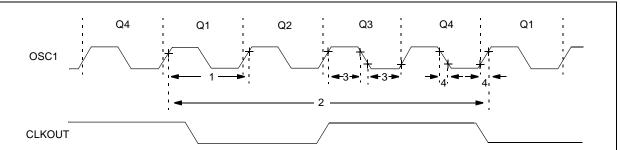


FIGURE 17-6: EXTERNAL CLOCK TIMING - PIC16C5X, PIC16CR5X

TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Charac	cteristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \\ \end{array} $						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
	Fosc	External CLKIN Frequency ⁽¹⁾	DC	_	4.0	MHz	XT osc mode	
			DC	—	4.0	MHz	HS osc mode (04)	
			DC	—	20	MHz	HS osc mode (20)	
			DC	—	200	kHz	LP OSC mode	
		Oscillator Frequency ⁽¹⁾	DC	—	4.0	MHz	RC osc mode	
			0.45	—	4.0	MHz	XT osc mode	
			4.0	—	4.0	MHz	HS osc mode (04)	
			4.0	—	20	MHz	HS osc mode (20)	
			5.0		200	kHz	LP OSC mode	
1	Tosc	External CLKIN Period ⁽¹⁾	250	—	—	ns	XT osc mode	
			250	—	—	ns	HS osc mode (04)	
			50	—	—	ns	HS osc mode (20)	
			5.0		—	μS	LP OSC mode	
		Oscillator Period ⁽¹⁾	250	—	—	ns	RC osc mode	
			250	—	2,200	ns	XT osc mode	
			250	—	250	ns	HS osc mode (04)	
			50	—	250	ns	HS osc mode (20)	
			5.0	—	200	μS	LP osc mode	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Chara	cteristics	-40°C	$C \le TA :$ $C \le TA :$	ss otherv ≤ +70°C f ≤ +85°C f ≤ +125°C	or com or indu	mercial strial	-
Param No.	Symbol	Characteristic Min Typ† Max Units Condition					
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc		—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50* 20*	_		ns ns	XT oscillator HS oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	2.0*	_	 25*	μS ns	LP oscillator XT oscillator
			_	_	25* 50*	ns ns	HS oscillator LP oscillator

- * These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- **Note 1:** All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

19.0 ELECTRICAL CHARACTERISTICS - PIC16LC54C 40MHz

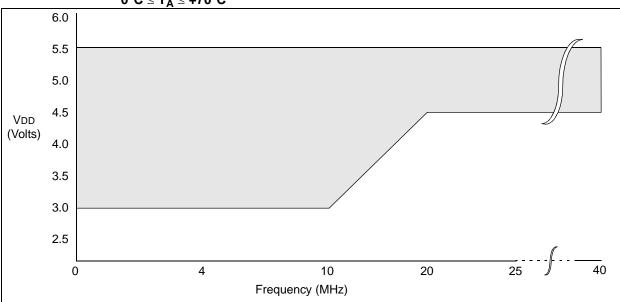
Absolute Maximum Ratings^(†)

Ambient temperature under bias	–55°C to +125°C
Storage temperature	–65°C to +150°C
Voltage on VDD with respect to VSS	0 to +7.5V
Voltage on MCLR with respect to Vss	0 to +14V
Voltage on all other pins with respect to Vss	–0.6V to (VDD + 0.6V)
Total power dissipation ⁽¹⁾	800 mW
Max. current out of Vss pin	150 mA
Max. current into Vod pin	
Max. current into an input pin (T0CKI only)	±500 μA
Input clamp current, liк (Vi <0 or Vi > VDD)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VDD)	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	20 mA
Max. output current sourced by a single I/O (Port A, B or C)	50 mA
Max. output current sunk by a single I/O (Port A, B or C)	50 mA
Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH)	x IOH} + Σ (Vol x Iol)

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC16C5X

FIGURE 19-1: PIC16C54C/C55A/C56A/C57C/C58B-40 VOLTAGE-FREQUENCY GRAPH, $0^{\circ}C \le T_A \le +70^{\circ}C$





- **2:** The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.
- **3:** Operation between 20 to 40 MHz requires the following:
 - VDD between 4.5V. and 5.5V
 - OSC1 externally driven
 - OSC2 not connected
 - HS mode
 - Commercial temperatures

Devices qualified for 40 MHz operation have -40 designation (ex: PIC16C54C-40/P).

4: For operation between DC and 20 MHz, see Section 17.1.









21.0 PACKAGING INFORMATION

21.1 Package Marketing Information

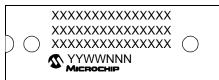
18-Lead PDIP



28-Lead Skinny PDIP (.300")



28-Lead PDIP (.600")



18-Lead SOIC



28-Lead SOIC

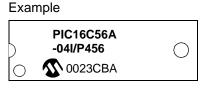


20-Lead SSOP



28-Lead SSOP

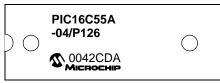




Example



Example



Example



Example



Example

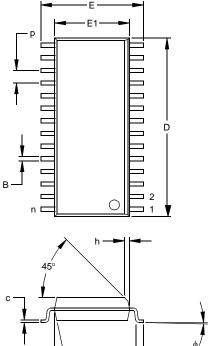


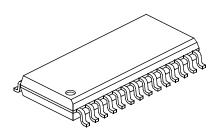
Example

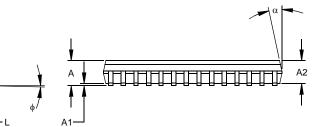


28-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

For the most current package drawings, please see the Microchip Packaging Specification located Note: at http://www.microchip.com/packaging







	Units	Units INCHES*			MILLIMETERS		
Dimensi	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n		28			28	
Pitch	р		.050			1.27	
Overall Height	А	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	φ	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.013	0.23	0.28	0.33
Lead Width	В	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-013 Drawing No. C04-052

APPENDIX A: COMPATIBILITY

To convert code written for PIC16CXX to PIC16C5X, the user should take the following steps:

- 1. Check any CALL, GOTO or instructions that modify the PC to determine if any program memory page select operations (PA2, PA1, PA0 bits) need to be made.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any special function register page switching. Redefine data variables to reallocate them.
- 4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change RESET vector to proper value for processor used.
- 6. Remove any use of the ADDLW, RETURN and SUBLW instructions.
- 7. Rewrite any code segments that use interrupts.

APPENDIX B: REVISION HISTORY

Revision KE (January 2013)

Added a note to each package outline drawing.